Matt Tin-Lead LA

Matt Tin-Lead LA is mainly applied for plating of printed circuit boards, but also for plating of other electronic components. The borofluoric acid based electrolyte deposits fine crystalline coatings. The tin content in the deposited coating is approx. 60 %, which can be varied depending on the chosen electrolyte composition. The electrolyte can be made-up in two variants. The common make-up allows current densities of 1 -3 A/dm². With reduced metal concentration current densities up to 1.5 A/dm² are possible. This variant has the advantage of less drag-out losses.

The Matt Tin-Lead LA is very economical. The organic additives are almost only consumed by electrolyte drag-out. All additives may be determined by analysis. Even after prolonged storage periods the coatings have excellent reflow characteristics and solderability, in oil- as well as in infrared operated plants.

With the help of the Stabilisers LA 3 and SLOTOTIN SN 9009 the oxidation of Sn(II) is inhibited. Stabiliser SLOTOTIN SN 9009 is a methanol-free variant.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.